

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	357	"257"/\$.ccls. and interposer with (epoxy resin) and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	133	"438"/\$.ccls. and interposer with (epoxy resin) and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	62	"361"/\$.ccls. and interposer with (epoxy resin) and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L4	29	"29"/\$.ccls. and interposer with (epoxy resin) and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
5	BRS	L5	656	"438"/\$.ccls. and interposer and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	120	"438"/\$.ccls. and interposer with (cavity hole) and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	61	"29"/\$.ccls. and interposer with (cavity hole) and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L8	95	"361"/\$.ccls. and interposer with (cavity hole) and (substrate carrier board) and (chip die ic) and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
9	BRS	L9	333	"257"/\$.ccls. and interposer with (cavity hole) and (substrate carrier board) and (chip die ic) and (bump ball)	US- PGPUB; USPAT; EPO; JPO; DERWEN T; IBM_TD B